L Number	Hits	Search Text	DB	Time stamp
1	21125	(smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:27
2	3248	(least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:29
3	361	((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:46
4	742	((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:58
5	576	(((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:47
6	105	(bump ball flip flipchip) and ((((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:56
7	2241072	(flipchip flip die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:53
8	403564	(least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:56
9	38492	(bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:31
10	2438	((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:30
11	15795	(smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:01

12	62	((smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))) and (((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin encapsulant epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:01
13	60	(((smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))) and (((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin encapsulant epoxy))) not ((bump ball flip flipchip) and ((((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
14	2534	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
15	1609	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
16	751	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
17	1434	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
18	2360	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
19	1583	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
20	1970	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:26
21	7081	257/723 257/686 257/685 257/777 257/778 257/738 257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:27
22	111413	(smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:29

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23	1552	((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) and (257/723 257/686 257/685 257/777 257/778 257/738 257/737)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:29
24	90288	((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) not ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:29
25	1359	(((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) not ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (257/723 257/686 257/685 257/777 257/778 257/738 257/737)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:29
26	1299	(least stacked multi multiple plurality) and ((((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) not ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (257/723 257/686 257/685 257/777 257/778 257/738 257/737))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:30
27	983	((least stacked multi multiple plurality) and ((((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) not ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (257/723 257/686 257/685 257/777 257/778 257/738 257/737))) and (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:31
28	755	(bump ball flip flipchip) and (((least stacked multi multiple plurality) and ((((smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))) not ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (257/723 257/686 257/685 257/777 257/778 257/738 257/737))) and (resin encapsulant epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 10:32

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